



リセハウジング外形
OUTLINE OF RECEPTACLE HSG.

HDR 外形
OUTLINE OF HEADER HSG.

スルーホール2-φ3.0 ±0.1
DIA 3±0.1 2PLACES

ラウンド2-φ4.0MIN
ROUND DIA 4MIN. 2PLACES

6-φ1.1
DIA 1.1± 6PLACES

(非累積公差)
推奨基板取付け穴寸法 (コネクタ搭載面)
RECOMEND PC BOARD HOLE PATTERN (NOT ACCUMULATE TOLERANCE)
PC BOARD THICKNEES; 1.6±0.1 (PC 基板厚; 1.6±0.1)

- 注記
- ① 材料;ハウジング;ガラス入りポリエステル樹脂
 CONTACT;銅合金 熱可塑性ポリエステル樹脂
 リテンションレグ;銅合金
 - ② めっき:(CONTACT接触部)ニッケル下地の上に0.38μMIN金メッキ
 - ③ めっき:(CONTACT接触部)ニッケル下地の上に0.76μMIN金メッキ
 - ④ めっき:(CONTACT全面)ニッケル下地の上に2.0μMINスズメッキ
 - ⑤ (リテンションレグとCONTACT半田付け部)ニッケル下地の上に半田メッキ
 - ⑥ めっき:リテンションレグとCONTACT半田付け部
 :ニッケル下地の上にスズめっき

- NOTES
- ① MATERIAL HOUSING:GLASS FILED POLYESTER
 CONTACT:COPPER ALLOY
 RETENTION LEG:COPPER ALLOY
 - ② FINISH(CONTACT AREA):0.38μMIN GOLD PLATED OVER NICKEL
 - ③ FINISH(CONTACT AREA):0.76μMIN GOLD PLATED OVER NICKEL
 - ④ FINISH(CONTACT):2.0 μMIN TIN PLATED OVER NICKEL
 - ⑤ FINISH(RETENTION LEG AND CONTACT TAIL):TIN-LEAD
 -PLATED OVER NICKEL
 - ⑥ FINISH(RETENTION LEG): TIN PLATED
 (CONTACT TAIL) OVER NICKEL

XY	⑥ ④	3-178137-5
	⑥ ③	3-178137-3
YY	⑥ ④	2-178137-5
	⑥ ③	2-178137-3
XX	⑥ ④	1-178137-5
	⑥ ③	1-178137-3
	⑥ ②	1-178137-2

C1	REVISED PER ECO-11-005030	RK	HMR	24MAR11
LTR	REVISION RECORD	DR	CHK	DATE

WIRE RANGE		INSULATION DIA		NAME	
mm ² (AWG -)		mmφ		DYNAMIC D-3100 3.81 X 7.62 PITCH(H) 6POS. HDR CONN. ASS'Y (KEY;XX,YY,XY)	
MATERIAL SEE NOTE 注記参照		FINISH SEE NOTE 注記参照		一般公差 (GENERAL TOLERANCE)	SIZE LOC NUMBER
DR. 1-JULY-'92 Y.TANAKA		DE. 1-JULY-'92 Y.TANAKA		10% ±0.3 10% 30% ±0.4 30% 100% ±0.45 角度: ±3'	A3 J C-178137
CHK. 6-JUL-'92 S.MANABE		APP. 6-JUL-'92 S.MANABE		SCALE	REV. SHEET
				2-1	C1 1 OF 1

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